

HT4500 Thermally Conductive Gap Filler

BENEFITS AND FEATURES

- One-part, pre-cured
- Low viscosity
- Dispensable and printable
- Reliable thermal performance
- No pump out and cracking risk

OVERVIEW

Honeywell HT4500 dispensable/printable gap filler is silicone-based and filled with advanced ceramic fillers. It is formulated to deliver high dispense rate for improved productivity, good gap filling ability under low pressure and low contamination to devices. The viscosity is modified for printing process. The material is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing.

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Memory & power modules
- Power electronics

Property	HT4500	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Color	Green	Visual
Thermal Conductivity (W/m-K)	4.5	ASTM D5470
Dispense Rate (g/min)	>40	90psi 30cc EFD syringe
Specific Gravity	3.3	ASTM D792
Volume Resistivity (Ohm-cm)	$>1.0 \times 10^{13}$	ASTM D257
Dielectric Strength (KV/mm)	5	ASTM D149
Storage Condition	RT	-
Shelf Life (month)	12	-

Honeywell Electronic Materials

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